## **PRODUCT / PROCESS CHANGE NOTIFICATION**

1. PCN basic data			
1.1 Company	Life.augmented	STMicroelectronics International N.V	
1.2 PCN No.		MDG/23/14068	
1.3 Title of PCN		JSCC (China) additional source in UFQFPN 5X5 32L, UFQFPN 7X7 48L and VFQFPN 8X8 68L package for listed products	
1.4 Product Category		STM8xx Listed Products STM32xx Listed Products	
1.5 Issue date		2023-10-25	

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	NEMETH KRISZTINA	
2.1.2 Phone	+49 89460062210	
2.1.3 Email	krisztina.nemeth@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	StatsChipPAC JSCC Jiangyin China

4. Description of change		
	Old	New
4.1 Description	Assembly lines / wire bonding: - JSCC (China) / Gold wire   - JSCC (China) / Gold wire - JSCC (China) / Copper Palladium wire additional source   - ASE Kaohsiung (Taiwan) / Gold wire - JSCC (China) / Copper Palladium wire additional source   - Packages: - JSCC (China) / Gold wire   - UFQFPN 5X5 32L - UFQFPN 7X7 48L   - and VFQFPN 8X8 68L - UFQFPN 5X5 32L   - and VFQFPN 8X8 68L - UFQFPN 7X7 48L   - and VFQFPN 8X8 68L - UFQFPN 7X7 48L   - and VFQFPN 8X8 68L - UFQFPN 7X7 48L	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change in Form, no change in Fit, no change in Function. Package darkness might change depending on molding compound. Pin1 identifier remain in the same corner but might slightly change in terms of form and positioning.	

5. Reason / motivation for change		
5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end assembly line to maintain state of the art service level to our customers thanks to extra capacity.	
5.2 Customer Benefit	SERVICE IMPROVEMENT	

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensure by ST internal tools

7. Timing / schedule		
7.1 Date of qualification results	2023-12-27	
7.2 Intended start of delivery	2024-01-08	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description	14068 MDG-GPM-RER2220 JSCC UQFN 32L_48L VQFN 68L CuPdAu wires STM32- reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-10-25

## 9. Attachments (additional documentations)

14068 Public product.pdf 14068 MDG-GPM-RER2220 JSCC UQFN 32L\_48L VQFN 68L CuPdAu wires STM32- reliability plan.pdf 14068 PCN14068\_Additional information.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	STM32G0B1CBU6		
	STM32G431C8U6		
	STM32G431CBU6		
	STM32L412KBU6		
	STM32L412KBU6TR		

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